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Editorial

Statement of Peer Review †

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- Type of peer review: single-blind
- Conference submission management system: EasyChair
- Number of submissions received: 73
- Number of submissions rejected at initial stage: 13
- Number of submissions sent for review: 60
- Number of submissions accepted: 26
- Acceptance rate: 35.6%
- Average number of reviews per paper: 2
- Total number of reviewers involved: 71

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